

**METHOD OF FORMING A PHOTO SENSOR ON SEMICONDUCTOR
WAFER WITH OVERLAPPED REGION**

Appl. No.	10/065,296	Confirmation No.	5720
Applicant	Liang-Hua Lin, Anchor Chen		
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No.			

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT

Sir:

5 In response to the final Office action of 08/25/2004, a request for continued examination is submitted and amendments to the above-identified application are as follows:

Amendments to the Specification begin on page 3 of this paper.

10 **Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.**

Amendments to the Drawings begin on page 8 of this paper and include

both an attached replacement sheet and an annotated sheet showing changes.

Remarks/Arguments begin on page 9 of this paper.

An Appendix including amended drawing figures is attached following
5 page 21 of this paper.